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Yangjie Technology recently launched several TO-247AC packaged FRED products. This series of products adopts platinum diffusion technology to control the carrier lifetime and uses a planar extension design, achieving extremely low reverse recovery charge and small reverse leakage. Under the same test conditions, it achieves a good trade-off between Qrr and VF, reducing switching losses while taking into account conduction losses, and achieving the optimal energy efficiency. The chip adopts an anti-high-temperature aging terminal design and advanced packaging technology, which enhances the reliability and stability of the product, ensuring long-term stable operation of the chip in complex environments. It is suitable for use in charging piles, household appliances, etc.

## New Product Announcement

1. Excellent performance: good switching characteristics, with good Vf-Qrr trade-off characteristics.
2. High reliability: the latest generation of planar epitaxial structure, multi-layer passivation, low leakage current, good reliability.
3. Technical support: has a professional FAE team to provide timely technical support and application guidance.

Product Name	Package	$V_{RRM}$ (V)	$I_O$ (A)	$I_{FSM}$ (A)	$V_F$ (V)	$T_{rr}$ ns	$T_j$ (°C)
MUR6060P	TO-247AC	600	60	600	1.80	50	175
MUR6060PL	TO-247AC	600	60	500	1.90	35	175
MUR7560PL	TO-247AC	600	75	500	2.00	35	175
MURU 7560P	TO-247AC	600	75	600	1.48	55	175
MURS7560PL	TO-247AC	600	75	540	2.10	33	175
MUR60120PL	TO-247AC	1200	60	450	3.00	45	175

